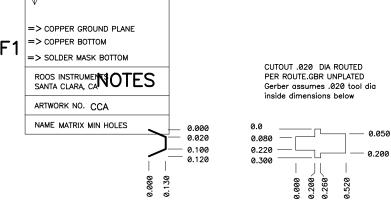




THIS LAYER



TOP SIDE GROUND PLANE, NEGATIVE
0.015 TRACE TOLERANCE +/- 0.002
0.006 SPACES AND 0.006 TRACES
NO LOADING LEGEND
SOLDER MASK IS A POSITIVE, APPLY 2 COATS
ALL HOLE DIAMETERS ARE AFTER PLATING
MATERIAL

FR-4, 0.010" +/- 0.002" CORE 1/2 OZ COPPER MIN BOTH LAYERS COPPER PLATING IN ALL HOLES TO BE .001 MINIMUM

FINISH, MINIMUM OF 50uIN HARD GOLD OVER 200uIN NICKEL.
CRITICAL AREA IS TOP SIDE GND PLANE FINGERS
IN 2 AREAS IN CENTER OF BOARD.
MUST BE ELECTROPLATED GOLD/NICKEL
NICKEL PER ASTM B689-97, TYPE2 CLASS 5
GOLD PER ASTM B488-01, TYPE 1, HARDNESS C, CLASS 0.50

CRITICAL HOLE LOCATION IS UNPLATED X TO ITS CLEARANCE PAD +-.002 LOCATE ALL PLTD HOLES WITHIN .003 OF PAD CENTER THIS DOCUMENT AND DATA ARE RI PROPRIETARY AND ARE DECLARED CONFIDENTIAL UNDER NON DISCLOSURE AGREEMENTS

HOLE SCHEDULE						
SYMBOL	QTY.	DIA.	TOL.+	TOL	PLATED	NOTES
+	231	.010	.004	.010	YES	VIAS (BASE=80)(RF=10)
x	22	.126	.001	.001	NO	DIB ALIGNMENT PINS
А	8	.210	.003	.003	NO	CLEARANCE
Y	32	.125	.003	.003	YES	DIB MOUNTING (BASE=15)
×	4	.063	.003	.003	NO	SOCKET
X	12	.110	.003	.003	NO	SOCKET
Т	4	.025	.003	.003	YES	PINS
	0		.003	.003		